



DOCUMENT TITLE:
MARKETING OUTLINE, 100L CHIP SCALE BGA (10X10) 0.8MM PITCH, 1.41 THICK, 2 LAYER

DOC ID # 21-0357 NEW REV: A

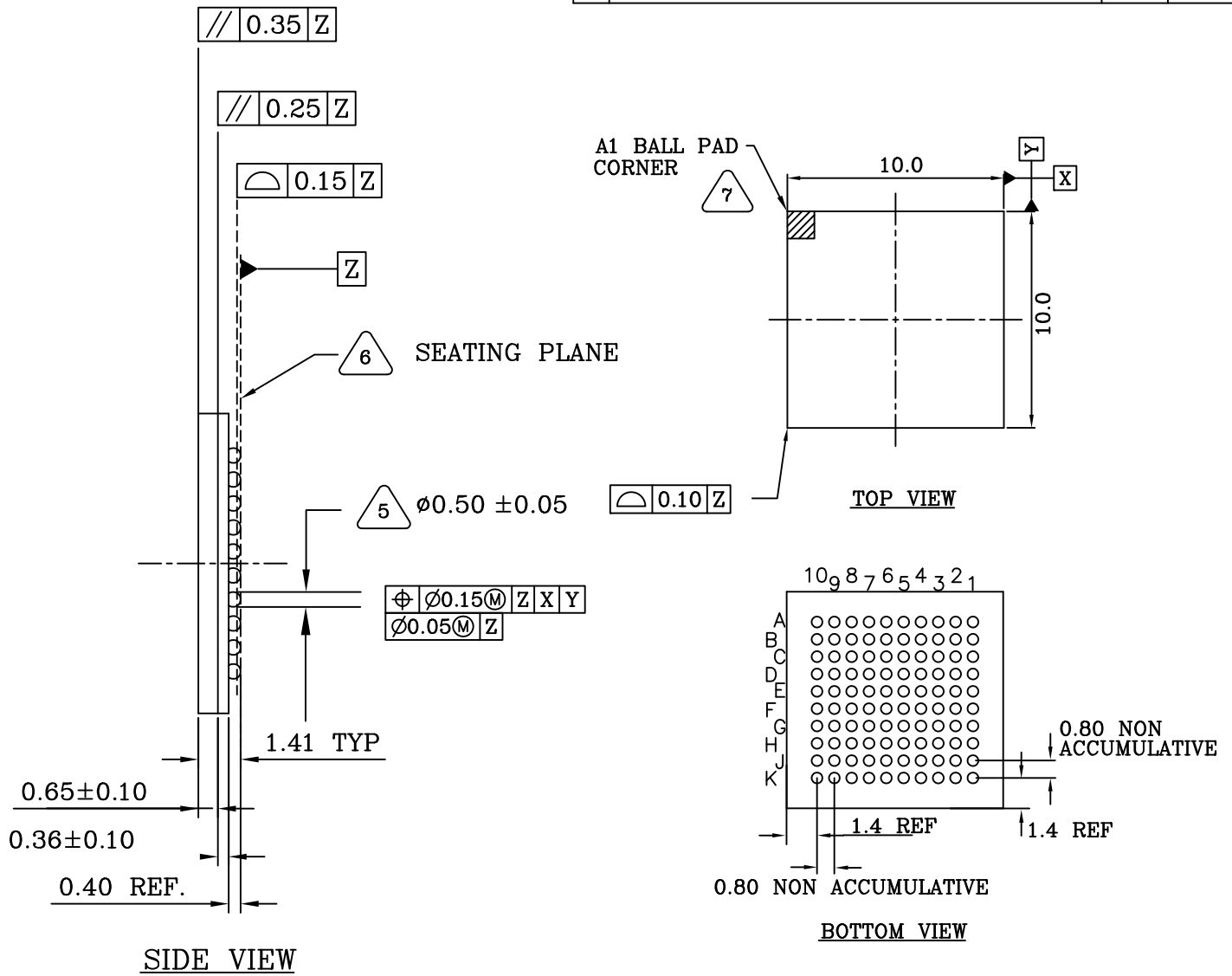
ECN#: HQ-08-5701 EFFECTIVE DATE: 07/15/08

ORIGINATOR: JEFF WALKER

MOST RECENT CHANGES

FROM	TO
DALLAS DOCUMENT CONTROL SYSTEM DOC 56-G6008-001 LOGO-DALLAS/MAXIM	INITIAL RELEASE INTO MAXIM DOCUMENT CONTROL LOGO-MAXIM

REVISIONS		
LTR.	DESCRIPTION	DATE
A		



NOTES:

7. A1 BALL PAD CORNER I.D. IS IDENTIFIED BY LASER MARKED DOT AT THE CORNER.
6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
4. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
3. SOLDER BALL POSITION DESIGNATION PER JESD 95-1, SPP-010.
2. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
1. ALL DIMENSIONS ARE IN MILLIMETERS

SIGNATURE		DATE		MAXIM			
DOC. CONTROL:							
ENGR. MGR:				TITLE			
MFG. ENGR:				MARKETING OUTLINE 100L CHIP SCALE BGA (10X10) 0.8MM PITCH, 1.41 THICK, 2 LAYER			
CHECKED BY:	TWM	8/00		SIZE	FSCN NO.	PART NO.	REV.
DRAWN BY:	JDH	8/00		A		21-0357	A
DO NOT SCALE DRAWING				SCALE	N/A	SHEET	1 of 1

REVISION HISTORY

REV	CHANGES MADE	DATE	INIT.
A	ECN# HQ-08-5701. INITIAL RELEASE INTO MAXIM DOCUMENT CONTROL. LOGO-MAXIM	07/15/08	JW



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